



AN10376

Mounting and soldering recommendations for CATV modules

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Application note

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1. Introduction

This document deals with the mounting and soldering of CATV modules.

2. Mounting and soldering recommendations

2.1 Mounting

The heatsink surface must be flat, free of burrs and oxidation and be parallel to the mounting surface.

The heatsink, mounting base and ground leads should be properly RF-grounded.

Heatsink compound should be applied sparingly and evenly on the mounting base. Suitable heatsink compounds are Dow Corning 340, Eccotherm TC-5 (E and C) and Wakefield 120.

When mounting CATV hybrid modules, the UNC screws must first be turned finger-tight. The screws should then be tightened to within the tolerance 0.5 Nm minimum and 0.7 Nm maximum.

2.2 Soldering

Modules may be soldered directly into a circuit using a soldering iron with a maximum temperature of 260 °C for not more than 3 seconds when the soldered joints are a minimum of 3 mm from the module.

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